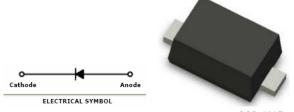


June 2008

# RB521S30 Schottky Barrier Diodes

- · Low Forward Voltage Drop
- Flat Lead, Surface Mount Device at 0.60mm Height
- Extremely Small Outline Plastic Package SOD523F
- Moisture Level Sensitivity 1
- Pb-free Version and RoHS Compliant
- · Matte Tin (Sn) Lead Finish
- · Green Mold Compound



SOD-523F Band Indicates Cathode\* Marking: 2B(521S)

## Absolute Maximum Ratings\* T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage	30	V
I <sub>F(AV)</sub>	Average Rectified Forward Current	200	mA
T <sub>J</sub>	Operating Junction Temperature Range -55 to +125		°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +125	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

### **Thermal Characteristics**

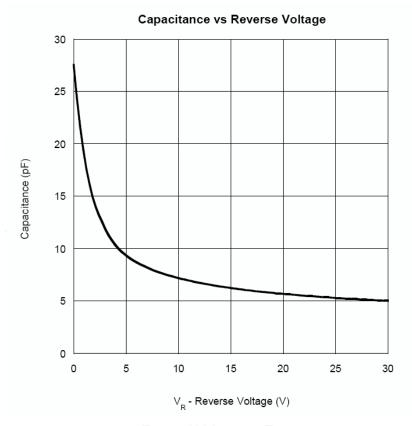
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	500	°C/W
P <sub>D</sub>	Total Device Dissipation(T <sub>C</sub> =25°C)	200	mW

<sup>\*</sup>Device mounted on FR-4 PCB minimum land pad.

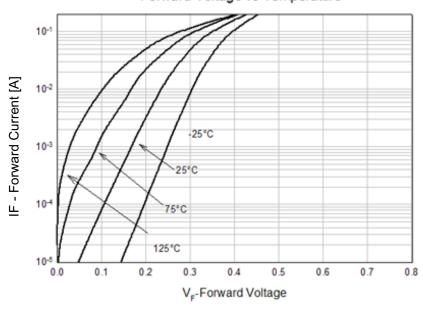
# Electrical Characteristics\* T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
BV <sub>R</sub>	Breakdown Voltage	I <sub>R</sub> = 500 μA	30			V
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 10 V			30	μΑ
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 200 mA			0.5	V

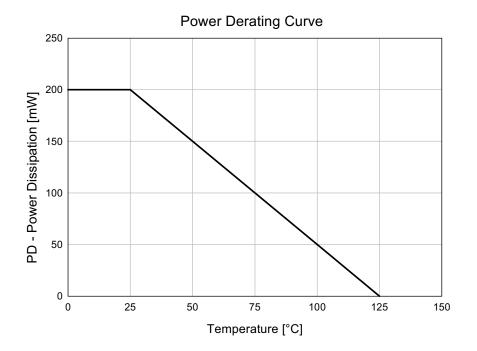
### **Typical Performance Characteristics**

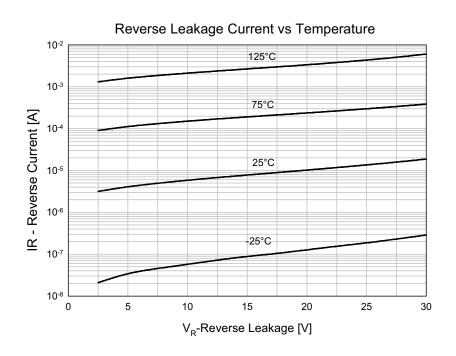


# Forward Voltage vs Temperature



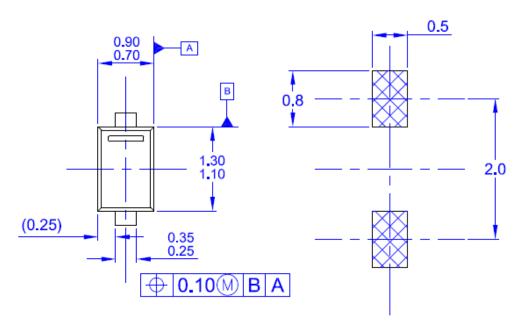
### **Typical Performance Characteristics**



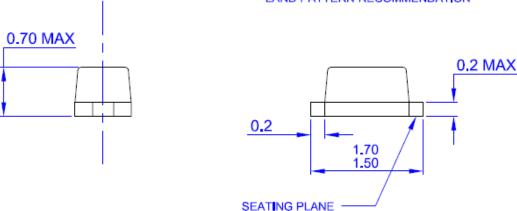


# **Package Dimension**

### **SOD-523F**



#### LAND PATTERN RECOMMENDATION



#### NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE REFERENCE; THIS PACKAGE OUTLINE CONFORMS TO JEITA SC-79.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DRAWING CONFORMS TO ASME Y14.5M 1994
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- E) LANDPATTERN RECOMMENDATION IS BASED ON IPC7351A STANDARD SOD1609X65M.
- F) DRAWING NUMBER AND REVISION MKT-SOD523F1rev1





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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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